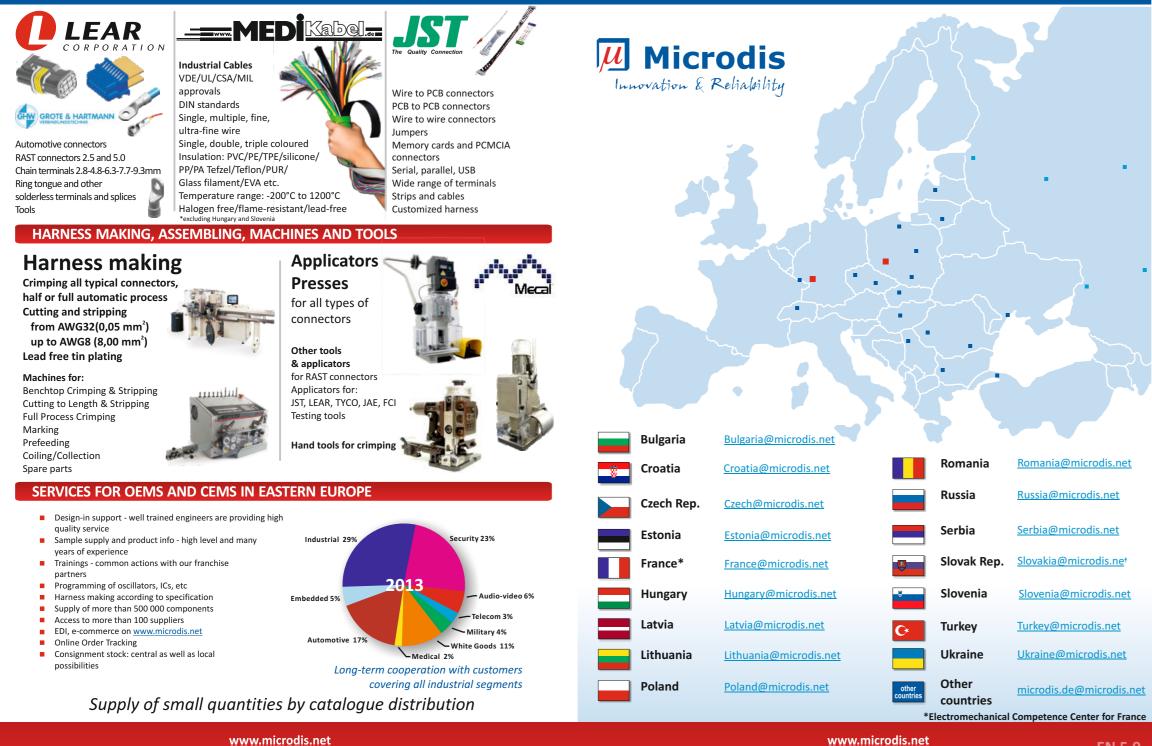
ELECTROMECHANICAL

CONTACT





25 YEARS OF MICRODIS ELECTRONICS

Leading in Eastern Europe as technical broadline distributor of electronic components, logistic provider and always reliable partner for suppliers and customers.

MICRODIS BUSINESS MODEL

- Franchise Distribution for a selected number of manufacturers
- Special Mass Market Distribution
- by Internet and Catalogue

Network Partnership with suppliers and customers









DEVELOPMENT STEPS OF THE MICRODIS ELECTRONICS GROUP 1989 Foundation of the companies in Hungary and Germany

- 1990 Foundation of sales companies in Poland and Slovakia First deliveries to the industry
- 1992 Foundation of LSB Electronics later renamed to Microdis Plus Poland Restructuring from retail to distribution
- 1993 Foundation of Microdis KFT in Hungary
- 1995 Consolidation of all companies within the Eurodis Microdis Holding AG in Switzerland (60% Eurodis [later Eurodis Electron PLC] and 40% Microdis) Foundation of a subsidiary in Czech Republic
- 2000 Europartners Consultants proclaimed Eurodis Microdis No. 1 in Poland and No. 3 in Hungary. Start of catalogue distribution
- 2003 Microdis sells its 40% shares of the Eurodis Microdis Electronics AG to Eurodis Electron PLC and takes over entirely Eurodis Microdis Electronics in Germany
- 2006 Microdis obtained ISO 9001:2000 Certification
- 2007 Foundation of Microdis in Ukraine
- 2008 Foundation of Microdis in Latvia
- 2009 Foundation of Microdis in Bulgaria
- 2010 Microdis Group obtained ISO 9001/2008 Certification 2011 Foundation of Microdis Components Elektronik in Turkey (Istanbul)
- 2012 Logistic Center moved to the acquired building in Hockenheim, Germany
- 2013 Inauguration of Electromechanical Competence Center for France, in Sarrebruck

25 years on the Eastern European market was truly a time of "Innovation and Reliability" that we are very proud of, and very grateful to all of our partners and friends. We look forward to a bright future together.

Microdis Electronics Team



www.microdis.net

WIRELESS TECHNOLOGY

RFID & EMBEDDED SYSTEMS

stol/mann

A M B E R



based on the latest technology u-blox8 New Form factors: MAX, NEO, LEA, EVA, PAM, CAM Modules are qualified for in vehicle use (ISO16750) High performance GNSS receivers, sensitivity: -167dBm Flexible modes, fe: GPS, Glonass, GPS+Glonass parallel Low cost versions (2 GSM bands) Extremely low power: 4.5mA/3V (fix GPS every 1s) Position accuracy (CEP, SBAS): 2.0m Built in active antenna support (power, monitor) High in-band jamming immunity, Jammer detection Assisted GNSS: GPS as well as Glonass supported, AssistNow Online, Offline and Autonomous modes Direct cooperation with GSM/UMTS modules PPP support – accuracy better than 1.0m (2D,R50) Dedicated modules for timing, RAW data Miniature modules with built-in antenna (CAM-M8Q)





GSM. GPS. GLONASS. Iridium. WiFi, ISM antennas Helical GPS & GLONASS antennas L1 & L2 band antennas HF connectors, adapter cables Evaluation kits and software



Reliable, field proven

GPS/Glonass/BeiDou/OZSS and GSM/UMTS/LTE modules

High performance GSM, UMTS, CDMA, LTE modules Navigation without GPS, based on GSM network eCall ready products with in-band modem Available in compact, SMT form factors Wide temperature range -40°C to +85°C



Field proven GSM/GPRS modules, families; LEON, SARA

LEON-G1, SARA-G3 - GSM/GPRS modules Embedded TCP/UDP/IP, FTP/HTTP/SMTP stack ATEX certificate to be used in explosive environments Low power consumption (<0.6mA idle, DRX9) Built-in Assisted GNSS client to support GNSS modules Multiple socket & IP addresses DTMF support, SIM card detection Small form factor 16.0x26.0x3.0mm One PCB design for GSM and UMTS modules Simple integration with u-blox' GNSS modules

SARA-U2 family of compact GSM/UMTS/HSPA modules

Form factor as small as 16.0x26.0x3.0mm Pin compatible to GSM/GPRS module SARA-G3 New Low cost version available (UMTS only, no GSM support) Low power consumption

> The smallest UMTS module: SARA-U2, pin compatible to SARA-G3 (GSM)

> > New

. TOBY family:

LTE modules

GSM/UMTS/HSPA+ modules

LISA-U2

HSDPA (21.1Mb/s), HSUPA (5.76Mb/s) Worldwide module All 3G (six) and 2G (four) bands support 3G: 800/850/900/1700/1900/2100MHz LISA family:WCDMA USB 2.0, SPI, UART worldwide module

TOBY – LTE modules TOBY-L1 – LTE only support TOBY-L2 - GSM/GPRS/HSPA+/LTE

Up to 150Mb/s data rate Voice over LTE

ested design available at u-blox, SARA, LISA or TOBY can be alternatively mounted on the same PCB

The use of u-blox modules does not lead to consequences from infringement of patents and copyrights.

ISM PRODUCTS

RF modules and modems

868MHz and 169MHz

Zigbee modules 4.5dBm power

Modems & USB Dongles

Certified industrial Bluetooth modules and Stacks (BT 2.1, 3.0 and BLE 4.0



ISO Cards, Key Fobs, Wrist Bands, PET laminates RFID system solutions for:Access control, Animal indentification(Pet, bird and livestock), Industry and logistic (also KEG and waste ID) The most popular standards on the market: 125kHz: EM Marin/Unique/Temic, Philips (Hitag) 13.56MHz: Philips (Mifare), Legic



SIM / Nano SIM / Pico SIM connectors Memory Card Connectors USB Connectors

Board to board connectors FFC connectors Dedicated white connectors for LED boards

Wireless M-Bus modules and devices for metering applications

Up to 320m Bluetooth range - Class 1)





Global Connector Technolog

INDUSTRIAL COMPUTING PRODUCTS



In-vehicle computers and displays Wireless communication: GPS, GSM, WLAN Flexible ignition control, easy adoption to car power-systems High vibration resistance, wide operating temperature Additional IP65 housing

Full HD Digital Signage Solutions

Wide range of industrial players designed for 24/7 operation Perfect graphic performance, various video outputs Single, dual, triple and quad display possibility

Panel PCs and fanless box computers for automation industry

Compact sizes, low power consumption Many options of I/O interfaces, high reliability Embedded OS, watchdog built-in, long life



IP67 Panel PCs. Industrial displays. Embedded boards Fanless with Intel, VIA and AMD CPUs, RISC Different form factors: FSB. HSB. 3.5". 5.25". PC/104 EPIC. ETX. ITX. XTX. COM. Oseven

/ISRock



Cost-effective and reliable mini-ITX boards Intel Atom/i3/i5/i7 and AMD G-series platforms Industrial design 5 Years life cycle support

ĭĭvama

32 - 65" Large Format Displays with Touchscreen

Fanless, great viewing angles and exceptional color clarity, wide range of video and audio nputs, dedicated space for nultimedia player mounting at the rear

SEMICONDUCTORS

ELECTROMECHANICAL

LIGHTING PRODUCTS

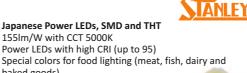
SEOUL SEMICONDUCTOR SEOUL

ACRICH2 - supplied directly from 230VAC. Luminous flux of one module up to 1450lm (17.5W), and up to 140lm/W efficacy (10W module)



Z-POWER LED - super bright power LEDs. Efficacy up to 160lm/W SIDE. TOP. CHIP. LAMP - available as through hole and SMD, ultrabright, multicolor, full-color (RGB), efficacy of 5630 LED up to 180lm/W (@65mA)





baked goods) 2000K for mood lighting LEDs for automotive market, IR LEDs



Double color (warm + cool) power LEDs Standard form factors 12W-36W (9090) 4-chip power LEDs Power LED matrix modules

Customized solutions

LED modules Square and round modules in different sizes LED strips Acrich2 modules Lighttubes



Design support and contract manufacturing



SEMICONDUCTOR

High quality semiconductors

Transient Voltage Suppressors Zener and switching diodes



Amplifiers and comparators Voltage references Industry standards:

78(9)xx, 78(9)Lxx, LM317, LM339, LM358, LM431, LM810, SMAJ, SMBJ, SMCJ, P4KE, P6KE, 1,5KE, BAV, BAS, BAT and many others

EPSON EXCEED YOUR VISIO

Timing and Sensing quartz based devices







RTC Modules

SAW Filters

Oscillators

TCXO

VCXO

Gyro sensors

Programmable Oscillators

Customer specified frequency (1.000MHz to 166.000MHz) Customer specified logic (5V, 3.3V, 2.5V, 1.8V) 10 sizes available including THT, SMD plastic package or SMD ceramic package

Available within 24h from stock!

QUARTZ+MEMS high accuracy and high stability Micro Electre Mechanical Systems

QMEMS is a combination of 'Quartz', a crystal material with excellent characteristics such as high stability and high precision, and "MEMS" (a microfabrication technology). To a semiconductor MEMS material, EPSON applies precision microprocessing based on quartz material to create a quartz device called 'QMEMS' which offers high performance in a compact package.



Push-pull circular connectors and cable assembly solutions

Generic connectors

Core Series – Brass connectors AluLite[™] Series – Aluminum connectors Plastic Series – Plastic connectors

Specific Connecors

Nim-Camac - Coax and Triax Connectors Disposable - Low cost, high performance connectors SD/HD Camera connectors – Triax or Fiber Optic UltiMate[™] - high performance military connectors



Wide range of electromechanical solutions

Tact Switches

Snap-in types available in 4.5x4.5mm to 12x12mm sizes Surface Mount types available in 2.8x2.4mm to 10x10mm sizes Sharp and Soft feeling types Multiple operating force versions (stem color coding) Dust proof & water proof versions available

Encoders

Multicontrol Devices

Memory and SIM card connectors also dedicated for automotive market

Detector switches

Magnetic, MEMS and capacitive sensors

Thermal Printers





Terminal blocks SPRINGCON - spring type RIACON - screw type PLUGCON - pin strips



elektronik 🕨 🗃

Machined extruded heatsinks Heatsinks for LEDs Extruded heatsinks with retaining springs for PCE mounting Heatsinks and fan coolers for processors, PGA & BGA components Cooling aggregates Thermal conductive materials



Cases Miniature aluminum cases Combination cases Desk consoles and shell cases 19" system cases

Connectors

Hi precision board-to-board connectors IDC connectors D-SUB connectors DIL PGA. PLCC sockets

Services Precision CNC machining of heatsinks, cases, front panels Powder coating Screen printing YAG laser engraving













IDCON - IDC - PCB connectors

Heatsinks



Rotary and slide potentiometers, industrial and pro-audio types available

Power Switches